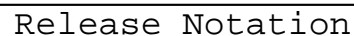
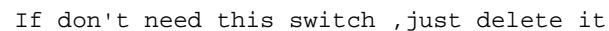
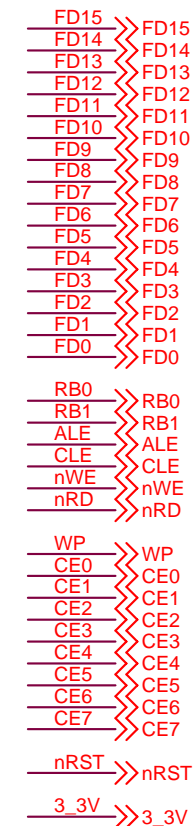
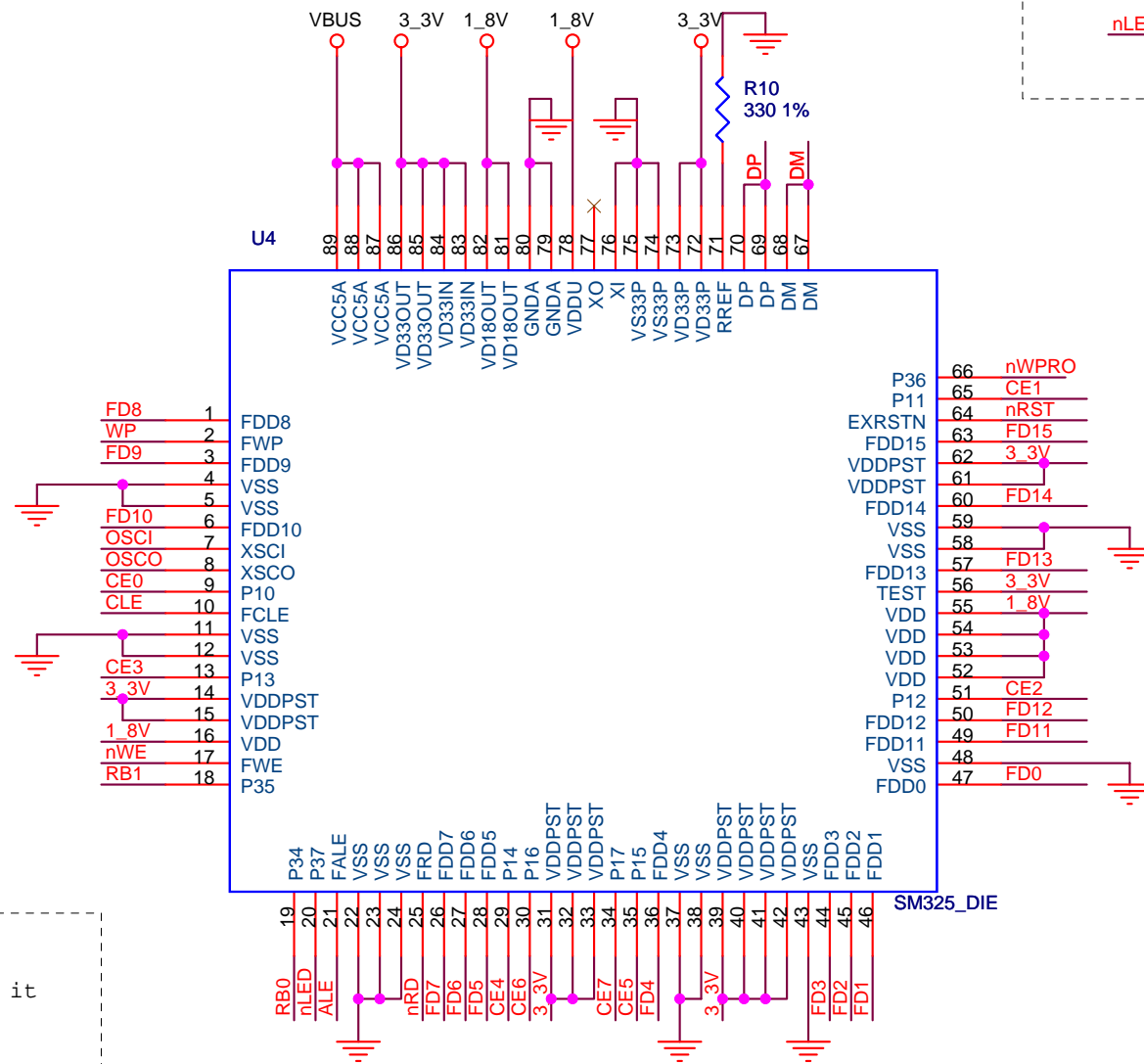


C3 allocate near U4 Pin78,80  
and same signal layer as U4



Date	Revision	Comments
2007.9	0.4	For SM325 ,First Release
2007.10	0.5	change pad 77 from GND to don't connection.
2008.01	0.6	delete L2,L26,L27,R13,C4,R20,R21,BC1,BC4 and BC8.



**Silicon Motion, INC.**

Title	MAIN
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Size  
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Document Number  
SM325\_DIE\_DEMO\_V06.DSN

Rev	0.6
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Date: Wednesday, January 16, 2008

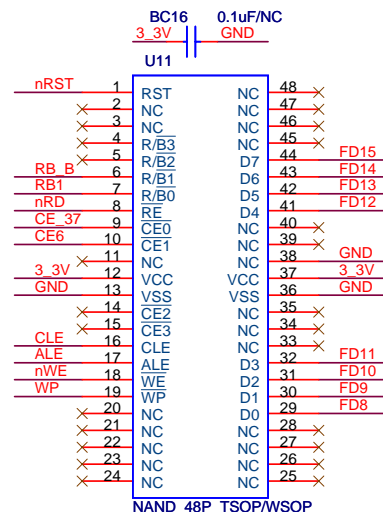
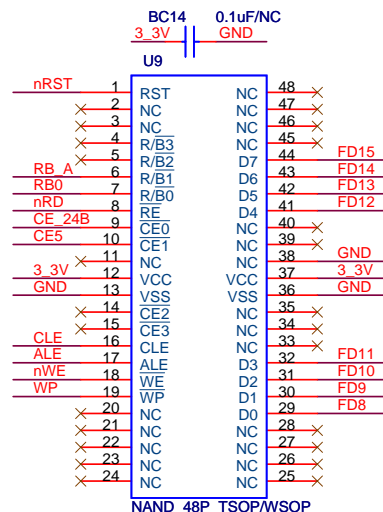
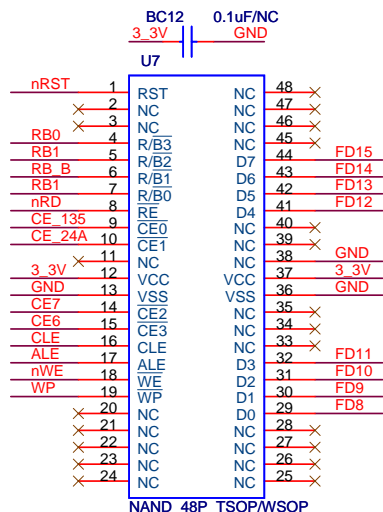
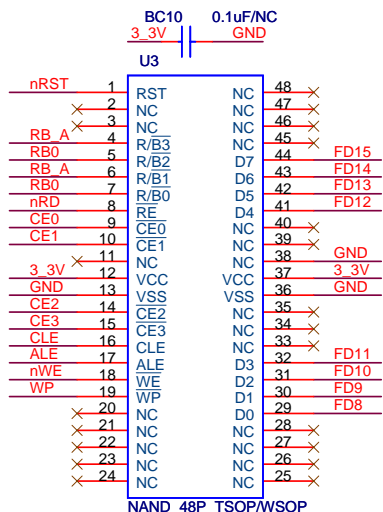
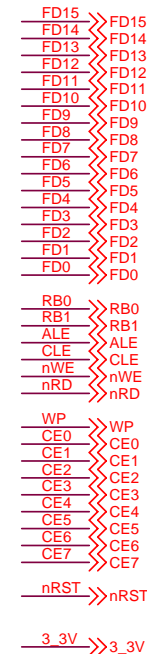
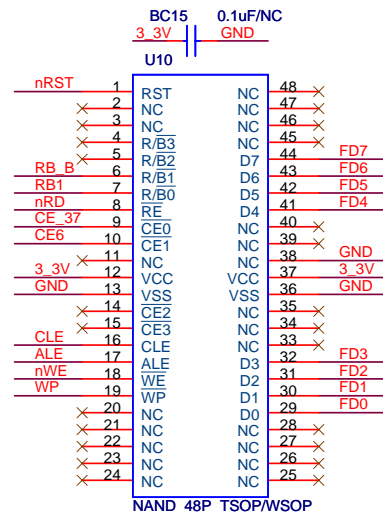
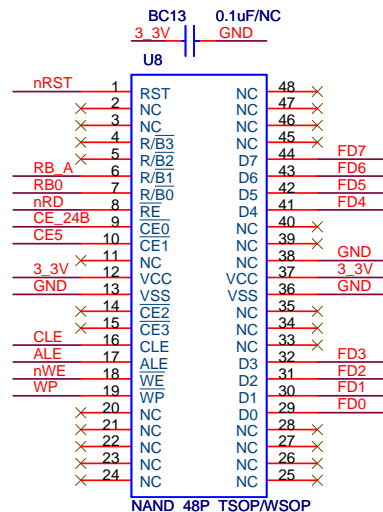
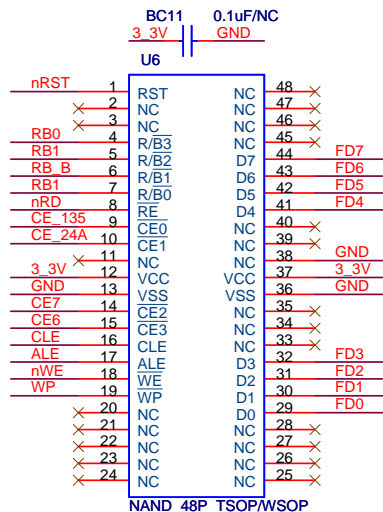
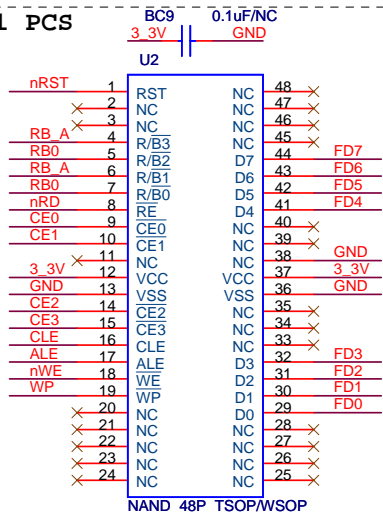
Sheet 1 of 2

## 8 PCS

## 4 PCS

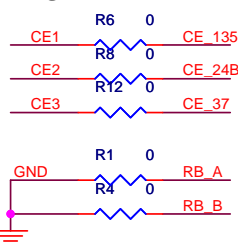
## 2 PCS

## 1 PCS

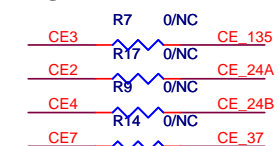


## Flash Setting

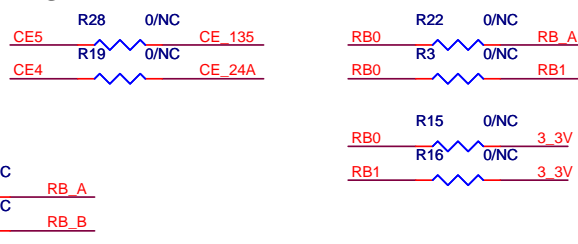
## 1 CE



## 2 CE



## 4 CE



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Title NAND FLASH		
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